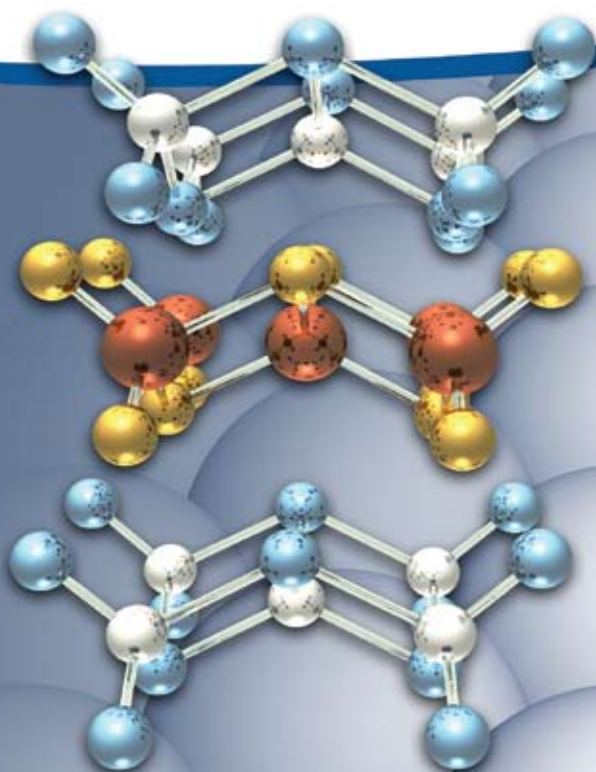


Material Matters™

Vol. 4, No. 2

ALDRICH
Chemistry

Advanced Ceramics Materials and Applications



Ceramics—more than just common materials

Iron Pnictide
Superconductors
High Temperature
Boron-based
Thermoelectric Materials
Silicon Carbide
Mesoporous Oxides and
Their Applications
to Hydrogen Storage

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Introduction

Ceramics can be broadly defined as nonmetallic inorganic solids consisting of infinite arrays of metal and nonmetal ions. The arrays do not form discrete units such as molecules or polymeric chains. As a rule, ceramics combine metal oxides, borides, carbides, arsenides, nitrides or other inorganic compounds into complex materials which have properties that differ considerably from those of the original constituents.

The name "ceramic" originates from the Greek word "keramos", which means "pottery". It can also be traced back to the word "Shrapika" meaning "potter" in Sanskrit.¹ For centuries, ceramic materials were manufactured by firing clay precursors, and most of the common ceramic products, such as tiles, cookware and bricks are still made this way.

Constantly growing demand for advanced materials in the 20th century resulted in the development of new classes of ceramic materials that do not originate in clays. Such materials, known as "Advanced Ceramics", are manufactured either from pure metal oxides by ceramic forming techniques,² or from other precursors using sol-gel processing,³ atomic layer deposition,⁴ or gas-phase synthesis.⁵ It wouldn't be an exaggeration to say that advanced ceramics play a crucial role in most areas of modern science and technology. Their applications comprise electronic materials and devices, nanomaterials, coatings, structural materials and composites.

Alternative energy is an area where advanced ceramics have proven to be particularly valuable. For example, high-temperature superconducting ceramic materials demonstrate great potential for reducing energy losses in electrical systems and devices, thus increasing their energy efficiency. Thermoelectric ceramics are capable of clean energy generation by transforming waste heat into electricity. Highly porous complex oxide systems find use as media for safe storage of energy rich gases such as hydrogen. Ceramics are also used as substrates for light emitting diodes, electrodes and electrolytes for solid oxide fuel cells (SOFC), highly efficient insulators etc.

The current issue of *Material Matters* features four articles that are concerned with applications of advanced ceramic materials in alternative energy and electronics fields. The issue begins with an article by Hideo Hosono from Tokyo Institute of Technology, Tokyo, Japan, that highlights novel superconducting ceramic materials recently developed by his group. Novel thermoelectric ceramics are discussed in the paper by Takao Mori from National Institute for Materials Science, Tsukuba, Japan, and silicon carbide based materials are reviewed in the article by Nicholas Wright and Alton B. Horsfall from Newcastle University, Newcastle, UK. Finally, the group led by Samuel Mao from the Lawrence Berkeley National Laboratory, USA, reports on the properties of nanoporous oxides for hydrogen storage and other energy related applications. The issue also highlights Aldrich Materials Science products for solid oxide fuel cell (SOFC) applications as well as ceramic nanomaterials, high-purity metal oxides and precursors for vapor deposition of ceramic thin films.

Customary to *Material Matters*, each article in this issue is accompanied by Sigma-Aldrich® products helpful in the corresponding type of advanced ceramics research. The facing page lists the materials categories that you will find in this issue. Please visit Aldrich Materials Science at sigma-aldrich.com/matsci for product information. We invite you to send your comments and questions regarding *Material Matters* and materials of interest to matsci@sial.com.

References:

- (1) http://www.iitk.ac.in/infocell/Archive/dirjuly3/techno_ceramics.html (last accessed May 5, 2009)
- (2) Carter, C.B., Norton, M.G. *Ceramic Materials*, Springer: New York, London, 2007.
- (3) *Material Matters* **2006**, 1, 3, 8-9.
- (4) *Material Matters* **2008**, 3, 2, 28-30.
- (5) *Material Matters* **2009**, 4, 1, 2-4.

About Our Cover

Ceramic materials have always been, and will continue to be, an inseparable part of human life. They are essential constituents in all modern technologies and devices including computers, displays, cars and spacecraft among others. Due to their unique combination of properties such as hardness, durability, high electrical and thermal resistivity and magnetic behavior, ceramic materials have become irreplaceable in a broad variety of applications. The most striking among them is the ability of certain complex ceramics to completely lose their electrical resistance at relatively high temperatures—an effect known as high-temperature superconductivity. The structure on the cover represents a group of high-temperature superconductors with the general formula LaFeAsO, developed at the Tokyo Institute of Technology. Read about these unique materials in Dr. Hosono's article on the pages 32-35.



Viktor Balema, Ph.D.
Materials Science
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Vol. 4 No. 2

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Joe Porwoll

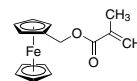
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Prof. Padma Gopalan of the University of Wisconsin, Madison, kindly suggested that we offer ferrocenylmethyl methacrylate (**Aldrich Prod. No. 700479**). The incorporation of metal containing moieties in block copolymer architecture lays the foundation for the inclusion of new functionalities to nanostructured materials. Examples include the incorporation of redox-active, photophysical, conductive, catalytic, or pre-ceramic functionalities. Polymers containing Ferrocene (**Aldrich Prod. No. F408**) have been widely used, largely due to their redox-induced morphological changes, their ability to serve as precursors for magnetic or catalytic materials and their use as plasma etch-resistant nano-templates. Ferrocenylmethyl methacrylate can be polymerized by a number of controlled radical polymerization techniques, which provide simple synthetic routes to a variety of functional polymers.

Ferrocenylmethyl methacrylate, 95% (NMR)

FMMA
[31566-61-7] C₁₅H₁₆FeO₂ FW 284.13



mp 52 to 54 °C

[700479-1G](#)

1 g

References:

- (1) Rider, D. A.; Liu, K.; Eloi, J.-C.; Vanderark, L.; Yang, Ling.; Wang, J.-Y.; Grozea, D.; Lu, H.-Z.; Russel, T.P.; Manners, I. *ACS Nano* **2008**, *2*(2), 263.
- (2) Sakakiyama, T.; Ohkita, H.; Ohoka, M.; Ito, S.; Tsujii, Y.; Fukuda, T. *Chem. Lett.* **2005**, *34*, 1366.

Advanced Ceramics and Other Materials Featured in this Issue*

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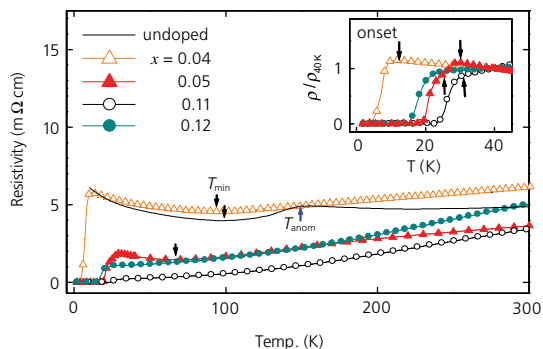
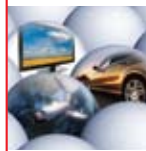


Figure 2. Temperature dependence of resistivity for $\text{LaFeAsO}_{1-x}\text{F}_x$ with x .

Emergence of T_c in LaFeAsO

Yoichi Kamihara, a postdoctoral fellow in charge of the Fe-system, attempted an aliovalent substitution of a doped carrier to LaFeAsO , following our previous experience with superconducting temperature (T_c) enhancement in LaFePO .⁵ The result was marvelous! Although no noticeable change was seen upon the doping of Ca to the La sites, F-doping to the O-site induced a drastic change in the ρ - T curves as shown in Figure 3. As the F-content increases, the kink around 150K disappears, and zero-resistivity begins to appear at $T > 4\text{K}$ for $F > 4\text{ mol\%}$. This temperature further increases up to 32K (onset) when fluorine content rises up to 11%. The observed zero-resistivity was confirmed as being due to superconductive transition in the bulk by measurements of magnetic susceptibility and heat capacity.

We noted that the emergence of T_c accompanies the disappearance of a sudden ρ -drop around 160K. Although T_c was found for LaFePO , LaNiPO , and LaNiAsO , we observed no such ρ -drop in any of them.

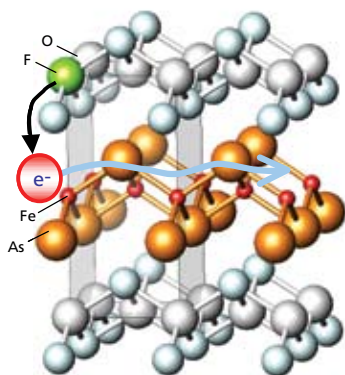


Figure 3. Crystal structure and role of F-doping in $\text{LaFeAsO}_{1-x}\text{F}_x$.

What happens around 150K in LaFeAsO ?

We assumed that the ρ -drop at $\sim 150\text{K}$ was closely related to the emergence of high T_c . This could be due to spin-ordering or a crystallographic phase transition. Although neutron diffraction is the best technique to check this possibility, we needed a lot of time to prepare the sample amount ($\sim 15\text{g}$) to acquire reliable data. Thus, we measured X-ray diffraction as soon as we could and obtained a beam time for the low-temperature powder XRD at Spring-8 as courtesy of Dr. Masaki Takata of RIKEN. The results of the XRD shown in Figure 4 were unambiguous.⁴ Crystallographic transition from tetragonal (Space group: $P4/nmm$) to orthorhombic phase ($Cmma$) was observed at $\sim 155\text{K}$ for the un-doped sample, but no such transition was observed for the F-doped, superconductive samples. A two-peak structure was observed in the heat-capacity measurement of the un-doped sample. The location of the high temperature peak agrees with that of the crystallographic transition.

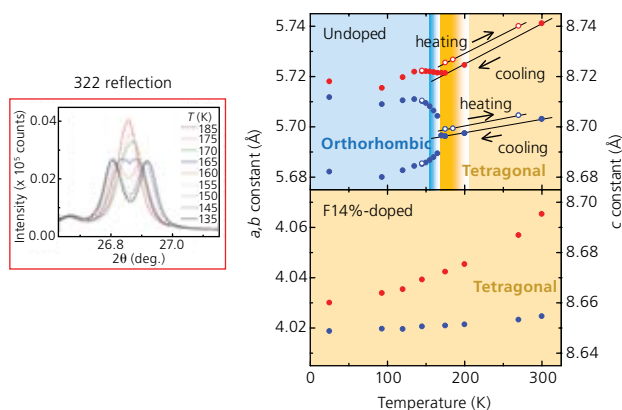


Figure 4. (Left) change in X-ray diffraction 322 peak of undoped LaFeAsO with temperature. (Right) Lattice constants of undoped and F14%-doped LaFeAsO as a function of temperature.

Local probe techniques, NMR on ^{139}La , and a Mossbauer spectroscopy of ^{57}Fe provided different information. Both measurements revealed that anti-ferromagnetic ordering occurred at $\sim 145\text{K}$, corresponding with the low-temperature heat capacity peak. But when electron carriers were doped, anti-ferromagnetic ordering continuously decreases and T_c appears, reaches a max, and then decreases.

Figure 5 is an electronic phase diagram of this system.

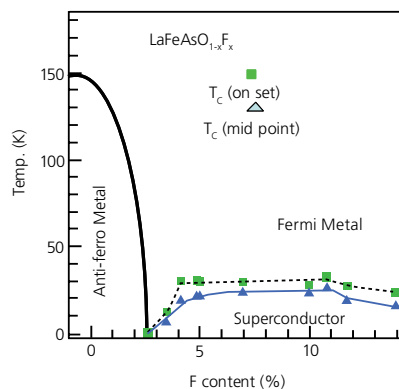


Figure 5. Electronic phase diagram of $\text{LaFeAsO}_{1-x}\text{F}_x$.



Figure 7 shows the T_c of some known superconductors versus the date of their discovery. The T_c in iron pnictide superconductors is second to high temperature cuprates, exceeding MgB_2 , which has the maximum T_c of conventional metal superconductors which can be explained by the BCS theory (electron-pairing required for superconductivity is mediated by lattice vibrations).

We have experienced that the old saying is mostly correct: “Strike while the iron is hot.” I hope cooperation and competition among active researchers will enhance the T_c of new superconductors toward the ultimate goal of room-temperature superconductors.

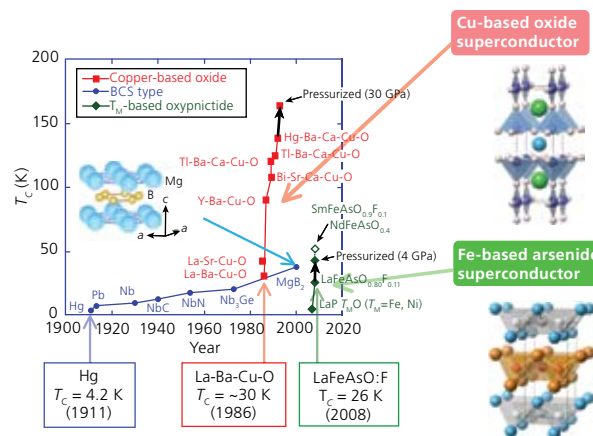


Figure 7. T_c of some known superconductors vs. the date of their discovery.

References:

- (1) Hosono, H.; Kamiya, T.; Hirano, M. *Bull. Chem. Soc. Jpn.* **2006**, *79*.
- (2) Miyakawa, M.; Kim, S.W.; Hirano, M.; Kohama, Y.; Kawaji, H.; Atake, T.; Ikegami, H.; Kono, K.; Hosono, H. *J. Am. Chem. Soc.*, **2007**, *129*, 7270.
- (3) Kawazoe, H.; Yasukawa, M.; Hyodo, H.; Kurita, M.; Yanagi, H.; Hosono, H. *Nature*, **1997**, *389*, 939.
- (4) Hosono, H. *J. Phys. Soc. Jpn.*, **2008**, *77SC*, 1.
- (5) Kamihara, Y.; Hiramatsu, H.; Hirano, M.; Kawamura, R.; Yanagi, H.; Kamiya, T.; Hosono, H. *J. Am. Chem. Soc.*, **2006**, *128*, 10012.
- (6) Watanabe, T.; Yanagi, H.; Kamiya, T.; Kamihara, Y.; Hiramatsu, H.; Hirano, M.; Hosono, H. *Inorg. Chem.*, **2007**, *46*, 7719.
- (7) Kamihara, Y.; Watanabe, T.; Hirano, M.; Hosono, H.; *J. Am. Chem. Soc.*, **2008**, *130*, 3296.
- (8) Takahashi, H.; Igawa, K.; Arii, K.; Kamihara, Y.; Hirano, M.; Hosono, H. *Nature*, **2008**, *453*, 376.
- (9) Ren, Z.A.; Lu, W.; Yang, J.; Yi, W.; Shen, X.L.; Li, Z.C.; Che, G.C.; Dong, X.L.; Sun, L.L.; Zhou, F.; Zhao, Z.X. *Chin. Phys. Lett.*, **2008**, *25*, 2215.
- (10) Sefat, A.S.; Mi, R.J.; McGuire, A.; Sales, B.C.; Singh, D.J.; Mandrus, D. *Phys. Rev. Lett.*, **2008**, *101*, 117004.
- (11) Jeitschko, W.; Glaum, R.; Boonk, L. *J. Solid State Chem.*, **1987**, *69*, 93.
- (12) Mine, T.; Yanagi, H.; Kamiya, T.; Kamihara, Y.; Hirano, M.; Hosono, H. *Solid State Commun.*, **2008**, *147*, 111.
- (13) Rotter, M.; Tegel, M.; Johrendt, D. *Phys. Rev. Lett.*, **2008**, *101*, 107006.
- (14) Hsu, F.-C.; Luo, J.-Y.; Yeh, K.-W.; Chen, Ta.-K.; Huang, T.-W.; Wu, P.-M.; Lee, Y.-C.; Huang, Y.-L.; Chu, Y.-Y.; Yan, D.-C.; Wu, M.-K.; *Proc. Natl. Acad. Sci. U.S.A.*, **2008**, *105*, 14262.
- (15) Malaeb, W.; Yoshida, T.; Kataoka, T.; Fujimori, A.; Kubota, M.; Ono, K.; Usui, H.; Kuroki, K.; Arita, R.; Aoki, H.; Kamihara, Y.; Hirano, M.; Hosono, H. *J. Phys. Soc. Jpn.*, **2008**, *77*, 093714.

Arsenides

For a complete list of metals, oxides, ceramics and related materials, please visit sigma-aldrich.com/ceramics

Name	Formula	Purity	Dimensions	Physical Form	Cat. No.
Iron(III) arsenide	FeAs	99.5% trace metals basis	-	pieces	709018-1G
Zinc arsenide	Zn ₃ As ₂	99.999% trace metals basis	-	pieces	709247-1G
Gallium arsenide	GaAs	99.999% trace metals basis	-	pieces	329010-1G 329010-5G
Gallium arsenide	GaAs	-	diam. × thickness 2 in. × 0.5 mm	<100> single crystal substrate	651486-1EA

Phosphides

Name	Formula	Purity	Dimensions	Physical Form	Cat. No.
Calcium phosphide	Ca ₃ P ₂	-	1 - 7 mm	chunks	400971-100G 400971-500G
Iron phosphide	Fe ₂ P	99.5% trace metals basis	-40 mesh	powder	691658-5G
Iron phosphide	Fe ₃ P	99.5% trace metals basis	-40 mesh	powder	691593-5G
Nickel phosphide	Ni ₂ P	98%	-100 mesh	powder	372641-10G
Gallium phosphide	GaP	99.99% trace metals basis	-	chunks	521574-2G
Indium(III) phosphide	InP	99.998% trace metals basis	3 - 20 mesh	pieces	366870-1G

Ferrites

Name	Formula	Purity	Dimensions	Physical Form	Cat. No.
Lithium iron(III) oxide	LiFeO ₂	95%	<1 μm	powder	442712-100G-A
Nickel zinc iron oxide	NiZnFe ₂ O ₄	≥99% trace metals basis	particle size <100 nm BET)	nanopowder	641669-10G 641669-50G
Copper iron oxide	CuFe ₂ O ₄	98.5% trace metals basis	particle size <100 nm BET)	nanopowder	641723-10G 641723-50G
Copper zinc iron oxide	CuZnFe ₂ O ₄	98.5% trace metals basis	particle size <100 nm BET)	nanopowder	641650-10G 641650-50G
Yttrium iron oxide	Y ₃ Fe ₅ O ₁₂	99.9% trace metals basis	particle size <100 nm BET)	nanopowder	634417-10G
Strontium ferrite	SrFe ₁₂ O ₁₉	99.8% trace metals basis	particle size <50 nm XRD) particle size <100 nm BET)	crystalline (hexagonal phase) nanopowder	633836-5G
Strontium ferrite	SrFe ₁₂ O ₁₉	99.5%	-325 mesh	powder	480371-5G 480371-25G
Barium ferrite	BaFe ₁₂ O ₁₉	99.5% trace metals basis	particle size <100 nm BET)	nanopowder	637602-25G
Barium ferrite	BaFe ₁₂ O ₁₉	98%	-325 mesh	powder	383295-250G 383295-1KG

Aluminates

Name	Formula	Purity	Dimensions	Physical Form	Cat. No.
Lithium aluminate	LiAlO ₂	-	-	powder and chunks	336637-250G
Sodium aluminate	NaAlO ₂	-	-	powder	13404-2.5KG-R 13404-5KG-R
Magnesium aluminate, spinel	MgO·Al ₂ O ₃	-	particle size <50 nm BET)	nanopowder	677396-5G
Copper aluminum oxide	CuAl ₂ O ₄	98.5% trace metals basis	particle size <50 nm XRD) particle size <100 nm BET)	nanopowder	634301-25G
Lanthanum aluminum oxide	LaAlO ₃	≥99.99% trace metals basis	10 × 10 × 0.5 mm	<100> single crystal substrate single side polished crystalline (rhombohedral at 25 °C (a = 5.357 Å, c = 13.22 Å); cubic at >435 °C (a = 3.821 Å))	634735-1EA
Aluminum cerium oxide	AlCeO ₃	99% trace metals basis	particle size <50 nm BET)	nanopowder	637866-10G 637866-50G



Nanomaterials

Aldrich Materials Science offers a wide range of inorganic nanopowders and nanoparticle dispersions, with products spanning the periodic table.

Inorganic nanomaterials, as well as technical articles on the controlled synthesis of nanomaterials, were featured in *Material Matters* Vol. 4, No. 1, which can be viewed online at sigma-aldrich.com/materialmatters.

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High Temperature Boron-based Thermoelectric Materials



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Introduction

The modern world is rapidly approaching the limits of classical energy reserves. Alternative sources of energy, such as the conversion of waste heat to electricity, offer potential and are an incentive to developing viable thermoelectric materials. In particular, materials that can function at high temperature and that withstand large temperature differences need to be developed for use in factories, power plants, incinerators, etc., as well as for reliable radiothermal generation of electricity in space applications.¹

Boron-rich cluster compounds typically have melting points above 2200 K, and are therefore attractive materials for such purposes. They are also non-toxic, lightweight, and show remarkable stability in corrosive and acidic environments. Their synthesis is relatively straight forward, the addition of small amounts of carbon, nitrogen, or silicon to rare earth-boron systems (RE-B), to serve as bridging sites, results in the formation of novel boron cluster structures.²

Boron-rich cluster materials typically exhibit low intrinsic thermal conductivity ($\leq 0.02 \text{ W cm}^{-1} \text{ K}^{-1}$) even for single crystals, which gives them "built in" merit as thermoelectric materials.²⁻⁴ The performance of thermoelectric materials is gauged by a dimensionless figure of merit ZT , where $ZT = \alpha^2 \sigma T / \kappa$, and α is the Seebeck coefficient, σ is the electrical conductivity, and κ the thermal conductivity. Therefore, in a system with low κ it is possible to concentrate on maximizing the power factor, $P = \alpha^2 \sigma$.

In this article, I focus on two novel boron-based compounds that have recently been discovered and that show promise in high temperature thermoelectric applications. The compounds are borosilicide, $\text{REB}_{44}\text{Si}_2$ (RE = rare earth) and homologous RE-B-C(N) borocarbides, including REB_{17}CN , $\text{REB}_{22}\text{C}_2\text{N}$, and $\text{REB}_{28.5}\text{C}_4$.

Emerging Boron-Based Materials and their Preparation

Boron is a versatile element, tending to form atomic networks based on clusters and 2D atomic nets in compounds. In this sense it is similar to carbon, which is able to form atomic network systems such as fullerenes, nanotubes, and graphite-related materials. Yet, the potential of boron in materials science is still largely untapped. Several striking properties of boron-containing compounds have recently been discovered, such as the superconductivity of MgB_2 ,⁵ (Aldrich Prod. No. [553913](#)) and boron-doped diamonds,⁶ the strong magnetic coupling in magnetically dilute insulators,² and the formation of a novel elemental structure of boron.⁷

Boron has one fewer electron than does carbon, which enables the formation of electron-deficient multi-atom networks. Such networks have a special affinity for the rare earth elements, which can supply electrons to the framework to stabilize and form novel structures (namely, new RE-B compounds), while the f electron shell is responsible for interesting properties, such as magnetism.^{2,8}

From an application standpoint, the boron cluster framework provides a light robust "armor" that is acid and corrosion resistant, and can withstand very high temperatures. Additional electronic, magnetic, and other useful properties can be supplied by the metal atom from the "inside." As noted earlier, the addition of small amounts of such elements as carbon, nitrogen, or silicon further increases the number of novel boron-based compounds that can be created.² The crystal structure of the $\text{REB}_{44}\text{Si}_2$ compounds is shown in **Figure 1a**. It consists of five crystallographically independent B_{12} icosahedra (20-sided polyhedra) and one B_{12}Si_2 polyhedron. In the framework, the rare earth atoms form ladders in the direction of the c -axis, along which one of the B_{12} icosahedra also forms a chain.

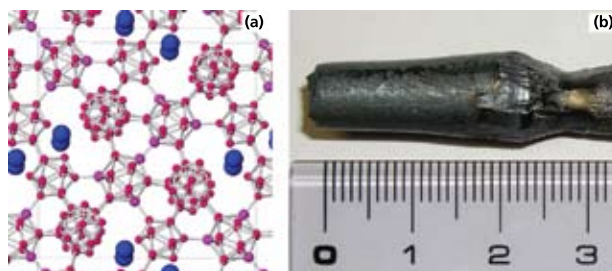


Figure 1. View of the (a) structure and (b) grown crystal of $\text{REB}_{44}\text{Si}_2$ (scale is cm).

Each of the rare earth-boron complexes $\text{REB}_{44}\text{Si}_2$, REB_{17}CN , $\text{REB}_{22}\text{C}_2\text{N}$, and $\text{REB}_{28.5}\text{C}_4$, can be synthesized in a similar way.² First, an appropriate rare earth oxide is reduced with boron (Aldrich Prod. No. [266620](#)) upon heating under vacuum. Then, required amounts of elemental silicon (Aldrich Prod. Nos. [633097](#), [343250](#), [267414](#)), carbon (Aldrich Prod. Nos. [699632](#), [699624](#), [496596](#), [496553](#)), or boron nitride (Aldrich Prod. No. [255475](#)) are added and heated again to produce the desired RE-B-X material. In the case of $\text{REB}_{44}\text{Si}_2$, it is possible to grow large crystals, as shown in **Figure 1b**.⁹



Borosilicides—New High Temperature p-Type Thermoelectric Materials

REB₄₄Si₂ compounds exhibit attractive high temperature thermoelectric properties.^{10,11} Their Seebeck coefficients gradually increase with temperature, exceeding 200 $\mu\text{V K}^{-1}$ above 1000 K (**Figure 2a**).¹⁰ A low intrinsic thermal conductivity of about 0.02 W cm⁻¹ K⁻¹ has also been reported (**Figure 2b**).¹¹ Unlike most thermoelectric materials, the figure of merit of REB₄₄Si₂ shows a steep increase at temperatures beyond 1000 K, where an extrapolated value for ZT of about 0.2 can be estimated.

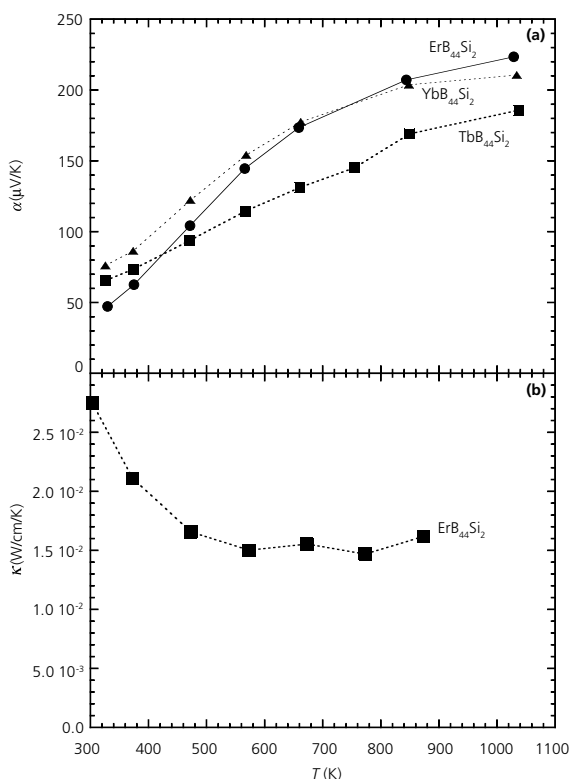


Figure 2. Temperature dependence of (a) Seebeck coefficient and (b) thermal conductivity of REB₄₄Si₂.

Considering that these compounds are not doped and are not composition optimized, their figure of merit and low intrinsic thermal conductivity indicate that they are good starting materials in the development of novel high temperature thermoelectric materials. It is noteworthy that the properties of boron carbide (**Aldrich Prod. No. 378119**), a classical thermoelectric material, can be significantly improved by controlling its carbon-boron composition.¹² Doping with transition metals is another way to efficiently modify the properties of REB₄₄Si₂. The transition metal atoms occupy voids between the boron clusters in the crystal lattice that, as indicated by our preliminary results, significantly increases the figure of merit of the doped material. Such doping efforts should be pursued further.

Control of the material's morphology is another avenue, which is being pursued since REB₄₄Si₂ compounds possess highly anisotropic crystal structures. The preparation of well-aligned materials can offer a powerful way to modify their thermoelectric properties.

Another advantage of REB₄₄Si₂ over boron carbide is its relatively low melting point (2200 K versus 2700 K), which allows easier processing. This, in conjunction with the properties previously mentioned, suggests that REB₄₄Si₂ can be an alternative to boron carbide as a high temperature p-type thermoelectric material, with the potential for further improvement through composition modification and doping.

RE-B-C(N) Borocarbides—Long Awaited n-Type Counterparts to Boron Carbide

The discovery of n-type RE-B-C(N) compounds is generating substantial interest due to their unique potential to serve as a high temperature thermoelectric counterpart to p-type boron carbide,^{13,14} since typical thermoelectric applications require both p- and n-type legs.

RE-B-C(N) compounds have a layered structure along the c-axis with B₁₂ icosahedra and C-B-C chain layers residing between the B₆ octahedral and the rare earth atomic layers (**Figure 3**). The number of interlayer B₁₂ icosahedra and C-B-C chain layers increases successively along the series REB₁₇CN, REB₂₂C₂N, and REB_{28.5}C₄. As the number of C-B-C layers approaches infinity (that is, no rare earth-containing layers), the compound is analogous to boron carbide.

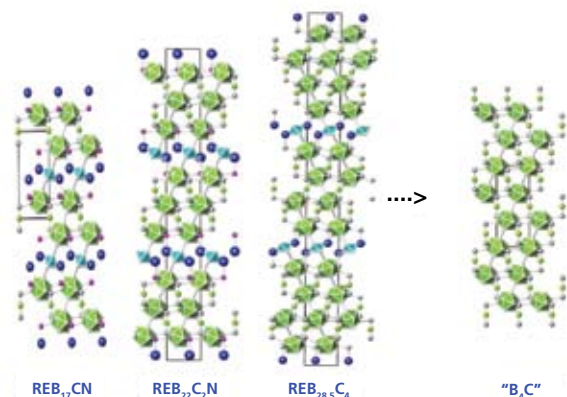


Figure 3. View of the structure of the homologous RE-B-C(N) compounds along the c-axis.

This similarity of RE-B-C(N) structural blocks to B₄C is the reason for considering them as compatible n-type counterparts to boron carbide, which has been established as an excellent p-type high temperature thermoelectric material.

One of the greatest challenges and opportunities for the RE-B-C(N) series is the development of an effective compaction procedure. Hot or cold pressing yields materials with densities of only about 50% of the theoretical value.¹³ Initial attempts to use spark plasma sintering (SPS) yielded an improvement to about 70% of the theoretical value, which is still rather low.¹⁴ The increase in density from 50% to 70% resulted in an increase in the figure of merit of close to two orders of magnitude. Therefore, the further development of a densification procedure is highly desirable.

An interesting way to control the morphology of RE-B-C(N) materials is by seeding them with a few percent of metallic borides (such as REB₆).¹⁴ While seeding does not impact densities, the Seebeck coefficients and the thermal conductivities of doped materials, the resistivities of these materials are reduced by up to two orders of magnitude, offering an effective way to increase the material's figure of merit. Since the percent of doping is small, it is unlikely that a percolation effect, where the metallic boride particles create channels of high electrical conductivity, is the reason for the observed effect. As seen in **Figure 4**, the metal-seeded sample has larger grain sizes than the undoped sample, indicating that the addition of metallic borides promotes grain growth in RE-B-C(N). We note that compared with conventional thermoelectric materials, in which it is usually preferred to inhibit grain growth in order to depress thermal conductivity, boron cluster compounds possess low intrinsic thermal conductivity, and therefore grain growth is beneficial. Thus, the seeding provides an efficient tool to control the morphology of the samples and to improve their thermoelectric properties.

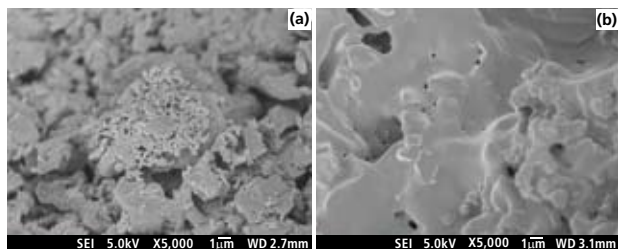


Figure 4. SEM microstructures of (a) $\text{YB}_{22}\text{C}_2\text{N}$ and (b) $\text{ErB}_{22}\text{C}_2\text{N}:\text{ErB}_4$.

RE-B-C(N) borocarbides demonstrate high anisotropy of the crystal structure (**Figure 3**), making further control of the nano- and microstructure of the samples a powerful tool for the enhancement, or tuning, of their thermoelectric properties. Further investigations should continue into the processing and densification of this system. It is hoped that this system will be a viable n-type counterpart to boron carbide.

Summary

Boron-based compounds are promising systems due to their high temperature thermoelectric properties. They are high temperature materials (typically possessing melting points above 2200 K), non-toxic, lightweight, and show remarkable stability in corrosive or acidic conditions. Two novel boron-based compounds are especially promising. $\text{REB}_{44}\text{Si}_2$ is a p-type high temperature compound that retains the low thermal conductivity exhibited by well known boron cluster compounds, such as REB_{66} , while improving the electrical properties and thermoelectric figure of merit. $\text{REB}_{44}\text{Si}_2$ can be more readily melted and therefore might be advantageous in processing when compared to boron carbide. The rare earth borocarbides, REB_{17}CN , $\text{REB}_{22}\text{C}_2\text{N}$, and $\text{REB}_{28.5}\text{C}_4$,

represent the first instance of intrinsic n-type behavior in boron cluster compounds, and are interesting as a highly compatible counterpart to boron carbide. Both compound systems have recently been discovered and further development should prove rewarding, since the benefits of finding materials able to viably convert high temperature waste heat to electricity are immense.

Research into the optimization and processing of these compounds has just begun. Composition control, carbon doping, and doping the voids of the clusters should greatly enhance the materials' thermoelectric properties. Optimizing densification processes for the borocarbides and ways to control the nano- and microstructure of both anisotropic compounds will be valuable tools in the further development of materials for high temperature thermoelectric applications.

References:

- (1) *Chemistry, Physics and Materials Science of Thermoelectric Materials: Beyond Bismuth Telluride*, Kanatzidis, M.G.; Mahanti, S.D.; Hogan, T.P., Ed.; Kluwer: New York, 2003.
- (2) Mori, T. *Handbook on the Physics and Chemistry of Rare Earths*, Gschneidner Jr, K.A.; Bunzli, J.C.; Pecharsky, V., Eds.; Elsevier:Amsterdam, 2008; Vol. 38; p 105.
- (3) Mori, T.; Martin, J.; Nolas, G. *J. Appl. Phys.* **2007**, *102*, 073510.
- (4) Cahill, D.G.; Fischer, H.E.; Watson, S.K.; Pohl, R.O.; Slack, G.A. *Phys. Rev. B*, **1989**, *40*, 3254.
- (5) Nagamatsu, J.; Nakagawa, N.; Muranaka, T.; Zenitani, Y.; Akimitsu, J.; *Nature*, **2001**, *410*, 63.
- (6) Ekimov, E. A.; Sidorov V.A.; Bauer E.D.; Mel'nik, N.N.; Curro N.J.; Thompson J.D.; Stishov, S.M.; *Nature*, **2004**, *428*, 542.
- (7) Oganov, A.R.; Chen, J.; Gatti, C.; Ma, Y.; Glass, C.W.; Liu, Z.; Yu, T.; Kurakevich, O.O.; Solozhenko, V.L.; *Nature* **2009**, *457*, 863.
- (8) Mori, T.; Tanaka, T. *J. Phys. Soc. Jpn.*, **1999**, *68*, 2033.
- (9) Mori, T. *Z. Krist.*, **2006**, *221*, 464.
- (10) Mori, T. *J. Appl. Phys.*, **2005**, *97*, 093703.
- (11) Mori, T. *Physica B*, **2006**, *383*, 120.
- (12) Wood, C.; Emin, D. *Phys. Rev. B*, **1984**, *29*, 4582.
- (13) Mori, T.; Nishimura, T. *J. Solid State Chem.*, **2006**, *179*, 2908.
- (14) Mori, T.; Nishimura, T.; Yamaura, K.; Takayama-Muromachi, E. *J. Appl. Phys.* **2007**, *101*, 093714.

Borides

For a complete list of metals, oxides, ceramics and related materials, please visit sigma-aldrich.com/ceramics

Name	Formula	Purity	Dimensions	Physical Form	Cat. No.
Magnesium boride	MgB_2	≥96%	–325 mesh	powder	553913-5G 553913-25G
Aluminum diboride	AlB_2	-	–325 mesh	powder	399612-5G
Aluminum dodecaboride	AlB_{12}	-	–325 mesh	powder	399604-5G
Calcium hexaboride	CaB_6	99.5%	–200 mesh	powder	394785-10G
Titanium boride	TiB_2	-	<10 µm	powder	336289-50G
Chromium diboride	CrB_2	≥99%	–325 mesh	powder	336750-50G
Cobalt boride, mixture of 2:1 and 3:1	-	99%	–10 mesh	powder	336777-5G 336777-25G
Nickel boride	Ni_2B	99%	–30 mesh	powder	372633-10G 372633-100G
Nickel boride	NiB	99% trace metals basis	–325 mesh	powder	709174-10G
Niobium monoboride	NbB	99.5%	–325 mesh	powder	399515-25G
Niobium diboride	NbB_2	-	–325 mesh	powder	399507-10G
Molybdenum boride	MoB	99.5% trace metals basis	–325 mesh	powder	709182-10G
Lanthanum boride	LaB_6	99.5% trace metals basis	–325 mesh	powder	709190-5G
Lanthanum hexaboride	LaB_6	99%	10 µm	powder	241857-25G
Gadolinium boride	GdB_6	99.5% trace metals basis	–325 mesh	powder	709212-10G
Hafnium boride	HfB_2	99.5% trace metals basis	–325 mesh	powder	709204-10G
Tantalum boride (1:1)	TaB	99.5%	–325 mesh	powder	336165-5G
Tantalum boride (1:2)	TaB_2	99.5%	–325 mesh	powder	336173-5G
Tungsten boride	WB	≥97.0%, gravimetric	-	powder	10497-25G

Nitrides

Name	Formula	Purity	Dimensions	Physical Form	Cat. No.
Lithium nitride	Li ₃ N	≥99.9%	–80 mesh	powder	399558-5G 399558-10G 399558-25G
Boron nitride	BN	98%	~1 μm	powder	255475-10G 255475-50G 255475-250G
Magnesium nitride	Mg ₃ N ₂	≥99.5% trace metals basis	–325 mesh	cubic phase powder	415111-10G 415111-50G
Aluminum nitride	AlN	≥98%	10 μm	powder	241903-50G 241903-250G
Aluminum nitride	AlN	≥98.5%	particle size <100 nm	nanopowder	593044-10G 593044-50G
Silicon nitride	Si ₃ N ₄	-	–325 mesh	predominantly α-phase powder	325171-50G 325171-250G
Silicon nitride	Si ₃ N ₄	≥98.5% trace metals basis	particle size <50 nm spherical)	nanopowder	636703-25G 636703-100G
Silicon nitride	Si ₃ N ₄	≥98% trace metals basis	particle size <50 nm BET)	nanopowder	634581-5G 634581-25G
Silicon nitride	Si ₃ N ₄	≥99.9% trace metals basis	<1 μm	powder	334103-25G 334103-100G
Silicon nitride	Si ₃ N ₄	-	–325 mesh	predominantly β-phase powder	248622-100G 248622-500G
Calcium nitride	Ca ₃ N ₂	95%	–200 mesh	powder	415103-25G 415103-100G
Titanium nitride	TiN	-	<3 μm	powder	595063-25G 595063-100G
Titanium carbonitride (7:3)	TiC _{0.7} N _{0.3}	≥97% trace metals basis	particle size <150 nm	nanopowder	636940-25G
Titanium carbonitride	TiCN	≥97% trace metals basis	particle size <150 nm spherical)	nanopowder	636959-25G 636959-100G
Gallium nitride	GaN	≥99.99% trace metals basis	-	powder	481769-10G 481769-50G
Germanium(III) nitride	Ge ₃ N ₄	≥99.99% trace metals basis	-	powder	447552-5G
Zirconium nitride	ZrN	≥99% trace metals basis	-	powder	594962-10G 594962-50G
Indium(III) nitride	InN	99.9% trace metals basis	100 mesh	powder	490628-1G 490628-5G

Rare Earth Oxides

Name	Formula	Purity	Physical Form	Cat. No.
Lanthanum(III) oxide	La ₂ O ₃	99.999% trace metals basis	powder	203556-100G 203556-500G
Lanthanum(III) oxide	La ₂ O ₃	99.99% trace metals basis	powder	199923-100G 199923-500G
Lanthanum(III) oxide	La ₂ O ₃	≥99.9%	powder	L4000-100G L4000-250G L4000-500G L4000-1KG
Cerium(IV) oxide	CeO ₂	99.995% trace metals basis	powder	202975-10G 202975-50G
Cerium(IV) oxide	CeO ₂	>99.95% trace metals basis	nanopowder	700290-25G 700290-100G
Cerium(IV) oxide	CeO ₂	-	nanopowder	544841-5G 544841-25G



Name	Formula	Purity	Physical Form	Cat. No.
Praseodymium(III) oxide	Pr ₂ O ₃	99.9% trace metals basis	powder	558249-10G 558249-50G
Praseodymium(III,IV) oxide	Pr ₆ O ₁₁	99.999% trace metals basis	powder	204145-2G 204145-10G
Praseodymium(III,IV) oxide	Pr ₆ O ₁₁	99.9% trace metals basis	powder	205176-50G 205176-250G
Neodymium(III) oxide	Nd ₂ O ₃	99.99% trace metals basis	powder	203858-10G 203858-50G
Neodymium(III) oxide	Nd ₂ O ₃	99.9% trace metals basis	powder	228656-25G 228656-100G
Neodymium(III) oxide	Nd ₂ O ₃	99.9% trace metals basis	nanopowder	634611-5G 634611-50G
Samarium(III) oxide	Sm ₂ O ₃	99.999% trace metals basis	powder	394394-5G 394394-25G
Samarium(III) oxide	Sm ₂ O ₃	99.99% trace metals basis	powder	392537-5G 392537-25G
Samarium(III) oxide	Sm ₂ O ₃	99.9% trace metals basis	powder	228672-10G 228672-100G
Europium(III) oxide	Eu ₂ O ₃	99.999% trace metals basis	powder and chunks	323543-1G 323543-5G
Europium(III) oxide	Eu ₂ O ₃	99.99% trace metals basis	powder	203262-5G 203262-25G
Europium(III) oxide	Eu ₂ O ₃	99.9% trace metals basis	powder	289221-5G 289221-25G
Gadolinium(III) oxide	Gd ₂ O ₃	≥99.99% trace metals basis	powder	203297-5G
Gadolinium(III) oxide	Gd ₂ O ₃	99.9% trace metals basis	powder	278513-25G 278513-100G
Terbium(III) oxide	Tb ₂ O ₃	99.99% trace metals basis	powder	590509-2G 590509-10G
Terbium(III,IV) oxide	Tb ₄ O ₇	99.999% trace metals basis	powder	204579-2G
Terbium(III,IV) oxide	Tb ₄ O ₇	99.9% trace metals basis	powder	253952-10G
Dysprosium(III) oxide	Dy ₂ O ₃	≥99.99% trace metals basis	powder	203181-5G 203181-25G
Dysprosium(III) oxide	Dy ₂ O ₃	99.9% trace metals basis	powder	289264-25G 289264-100G
Holmium(III) oxide	Ho ₂ O ₃	99.999% trace metals basis	powder	229679-1G 229679-10G
Holmium(III) oxide	Ho ₂ O ₃	≥99.9% (rare earth content, expressed as Ho ₂ O ₃)	powder	H9750-10G H9750-50G
Erbium(III) oxide	Er ₂ O ₃	≥99.99% trace metals basis	powder	203238-5G 203238-25G
Erbium(III) oxide	Er ₂ O ₃	99.9% trace metals basis	powder	289248-25G
Thulium(III) oxide	Tm ₂ O ₃	99.99% trace metals basis	powder	204676-1G
Thulium(III) oxide	Tm ₂ O ₃	99.9% trace metals basis	powder	289167-1G 289167-5G
Ytterbium(III) oxide	Yb ₂ O ₃	99.99% trace metals basis	powder	204889-10G
Ytterbium(III) oxide	Yb ₂ O ₃	99.9% trace metals basis	powder	246999-10G 246999-50G
Lutetium (III) oxide	Lu ₂ O ₃	99.99% trace metals basis	powder	203661-1G 203661-5G
Lutetium (III) oxide	Lu ₂ O ₃	99.9% trace metals basis	powder	289191-1G 289191-5G

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202975	Cerium (IV) oxide	99.995%
450804	Copper (II) oxide	99.995%
590509	Terbium (III) oxide	99.99%
463744	Vanadium (III) oxide	99.99%
554847	Barium oxide	99.99%
675644	Chromium (VI) oxide	99.99%
566284	Copper (I) oxide	99.99%
203238	Erbium (III) oxide	99.99%
215066	Gallium (III) oxide	99.99%
518158	Iron (II/III) oxide	99.99%
203815	Molybdenum (VI) oxide	99.99%
203394	Hafnium oxide	99.95%
415138	Strontium oxide	99.9%

Silicon Carbide: The Return of an Old Friend



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Introduction

In recent years silicon carbide, SiC, has re-emerged as a vital technological material that is crucial in many materials and engineering applications. Interestingly, SiC is one of the few minerals that were first created synthetically and subsequently discovered in nature. It was first artificially synthesized in 1891 by Edward Acheson as a result of unexpectedly discovering small black crystals of SiC in an electrically heated melt of carbon and alumina.¹ The subsequent refinement of this technique (the so-called Acheson process) led to the commercial production of large volumes of small SiC crystals (ground into powder form) for use as an industrial abrasive.² In 1905, silicon carbide was observed in its natural form by the Nobel-prize-winning chemist Henri Moissan in Diablo Canyon, Arizona. The transparent mineral, now known as moissanite, is almost as brilliant and as hard as diamond, and is therefore often used as a gemstone. To date, no large natural deposits of SiC have ever been found in nature so all SiC used today is synthetic.

In the present day, SiC is one of the most widely used materials that plays a critical role in industries such as: aerospace, electronics, industrial furnaces and wear-resistant mechanical parts among others. Although SiC is widely used in electronics and other high technology applications, the metallurgical, abrasive, and refractory industries are dominating by volume.

Crystal Structure

Silicon carbide has a layered crystal structure which occurs in a number of different forms or polytypes. Composed of carbon and silicon, in equal amounts, each atom is bonded to four atoms of the opposite type in a tetrahedral bonding configuration. There are three possible arrangements of atoms in a layer of SiC crystal known as the A, B and C positions, and each polytype has the same layers but a different stacking sequence (see Figure 1).³ As a given layer may be stacked on top of another in a variety of orientations (with both lateral translations and rotations being feasible energetically), silicon carbide may occur in a wide variety of stacking sequences—each unique stacking sequence generating a different polytype (e.g., cubic, hexagonal and rhombohedral structures can all occur). The hexagonal and rhombohedral structures, designated as the α -form (noncubic), may crystallize in a large number of polytypes whilst, to date, only one form of cubic structure (designated as the β -form) has been recorded. Designation⁴ is by the number of layers in the sequence, followed by H, R, or C to indicate whether the type belongs to the hexagonal, rhombohedral, or cubic class. To date, over 215 polytypes have been recorded—although only a limited number are of interest technologically (principally the 4H and 6H hexagonal plus the 3C cubic forms).⁵

This interest is driven by the commercial availability of substrates and the low mobility anisotropy (difference in carrier mobility with crystallographic direction) for these polytypes.

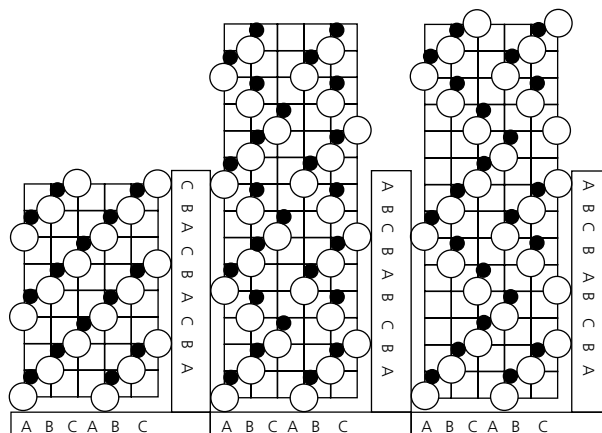


Figure 1. Stacking sequences of the Crystal structures of (a) 3C SiC, (b) 4H SiC, and (c) 6H SiC.

The term “silicon carbide” is commonly used to describe a range of materials that are in fact quite distinct. Mechanical engineers may use it to describe ceramics which are fabricated from relatively impure SiC crystallites bonded together with various binders under temperature and/or pressure, while electrical engineers may use the term to describe high purity single crystal wafers of SiC.

Applications Based on Mechanical Properties

All forms of silicon carbide are well known as hard materials occupying a relative position on Mohs' scale between alumina at 9 and diamond at 10.⁶ Because of its high thermal conductivity and low thermal expansion, silicon carbide is very resistant to thermal shock as compared to other refractory materials.⁶ Until the recent emergence of silicon carbide as a significant material for electronics, the mechanical properties of SiC-ceramics were the dominant commercial interest.

The formation of SiC powder is an essential pre-requisite to the manufacturing of many types of ceramic articles, which are subsequently obtained by shaping the manufactured silicon carbide powder. SiC powders with variable purity levels, crystal structures, particle sizes, shapes, and distributions can be prepared via several routes. Methods that have been examined include: growth by sublimation carbothermic reduction (the Acheson Process), conversion from polymers and gas phase chemical reactions.

Although brittle in nature, silicon carbide ceramics are leading materials for rotating and static components in many mechanical applications. They are characterized by low fracture toughness and limited strain-to-failure as compared to metals. The strength of a silicon carbide ceramic component is generally determined by pre-existing flaws introduced into the material during processing. The type, size, shape, and location of the flaws vary considerably and, consequently, so does the strength. Silicon carbide ceramics made by different techniques also have quite distinct mechanical properties. For example, sintered silicon carbide retains its strength at elevated temperatures and shows excellent time-dependent properties such as creep and slow crack growth resistance. In contrast, reaction-bonded SiC, because of the presence of free silicon in its microstructure, exhibits slightly inferior elevated temperature properties.⁷



The extreme hardness of silicon carbide leads to its use as a coating when wear resistance is important, such as brake linings and electrical contacts, and in non-slip applications such as floor or stair treads, terrazzo tile, deck-paint formulations, and road surfaces. SiC is also commonly used in mechanical seals found in pumps, compressors, and agitators in a wide variety of demanding environments including highly corrosive ones. Silicon carbide is harder, yet more brittle, than other abrasives such as aluminum oxide (Aldrich Prod. Nos. 202606, 342750). Because the grains fracture readily and maintain a sharp cutting action, silicon carbide abrasives are usually used for grinding hard, low tensile-strength materials such as chilled iron, marble, and granite, and materials that need sharp cutting action such as fiber, rubber, leather, or copper. Silicon carbide is also used in a loose form for lapping; mixed with other materials to form abrasive pastes, or used with cloth backings to form abrasive sheets, disks, or belts.⁶

Applications Based on Electronic and Optical Properties

In recent years, SiC has emerged as a promising material for electronics.^{8,9} Silicon carbide is considered a wide bandgap material since the electronic bandgaps of the different polytypes range from 2.4eV to 3.3eV (c.f., silicon with a bandgap of 1.1eV).¹⁰ In some respects, such a wide range of bandgaps is unexpected—particularly when the crystal structures of the polytypes differ only in the stacking sequence of otherwise identical bilayers (see Figure 1). Research in recent years has enabled the development of processing techniques that enable the material properties of silicon carbide to be modified successfully for electronics, in particular power electronics and sensors.¹¹ In addition, silicon carbide is commonly used as a substrate material for light emitting diodes where it acts as a foundation on which optically active layers can be grown. This growth utilizes the close lattice match between 6H SiC, gallium nitride and the high thermal conductivity of SiC to remove the heat generated in the LED.

One application where silicon carbide is making a big impact is gas sensors.¹² Its wide band gap gives it very low intrinsic carrier concentration, making sensing possible in very hot gases, such as the pollutants released in combustion engines and the sulphurous emissions from volcanic vents. A typical silicon-carbide gas sensor is about 100 μm across and a fraction of a millimeter thick, and are typically based on a capacitor (MIS structure) with a catalytic contact as shown in Figure 2.¹³ The dielectric layer allows these devices to operate at temperatures in excess of 900°C,¹⁴ by separating the metal from the silicon carbide. In this technology, dielectric layers are typically metal oxide materials such as TiO₂, or HfO₂ (Aldrich Prod. Nos. 203394 and 202118), which can be deposited in a variety of manners—including in-situ oxidation of metal layers or more sophisticated techniques such as Atomic Layer Deposition with relevant precursors.¹⁵ When the metal surface is exposed to a gas mixture, it speeds up the breakdown of the gas molecules, releasing ions that modify the electrical properties of the device. For hydrogen and hydrogen containing molecules, the hydrogen atoms can diffuse easily through thick or dense catalytic contacts to form the charged layer following decomposition of the gas molecule that occurs at temperatures above 150 °C in the sub-millisecond time scale.¹⁶ The response of the sensor can be measured via a number of methods including: capacitance shift, voltage shift required to maintain capacitance, or the leakage current through the dielectric layers. The high electrical response speed makes silicon carbide sensors suitable for the detection of gas species in rapidly varying environments, such as close to the manifold region in car exhausts,¹⁷ unlike conventional ceramic based sensors, which have a response time in the region of 10 seconds under these conditions.¹⁸

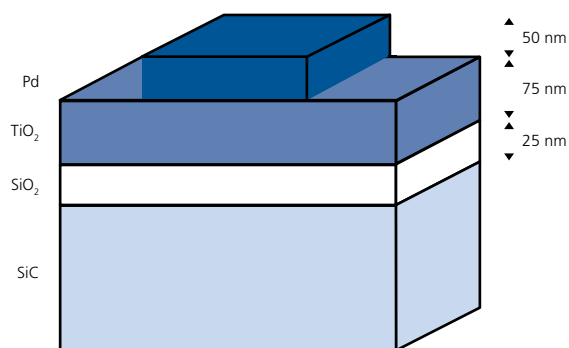


Figure 2. Cross-section of a SiC gas sensor. The SiO₂ layer is used to reduce the leakage current at high operating temperatures, due to the high band offsets and to reduce the defect density at the SiC/SiO₂ interface (Figure reproduced with permission from ref. 14. © 2007 IEEE). The SiC comprises a heavily doped substrate, which is typically 350 μm thick and a lightly doped epilayer of a few μm thickness.

Disentangling the effects of the different gases to determine the composition of a mixture is not easy. At temperatures above 600 °C the gas species dissociate completely at the metal surface, making it impossible to identify individual gases. For example, molecules of methane and ethane produce four and six hydrogen ions, respectively, when completely dissociated. This means that we cannot distinguish between a given concentration of methane and two-thirds of that concentration of ethane since both produce the same number of hydrogen ions. Below a temperature of 150 °C, the dissociation of gas species at the catalytic surface does not occur and the sensors do not respond to the gas at all. Between 150 °C and 600 °C the gas species dissociate only partially, and an array of sensors, with different characteristics to uniquely identify the gases present, can be used. For example, palladium is more sensitive to hydrogen and platinum to ammonia, so using one sensor with each metal allows these gases to be distinguished. Complex computer algorithms such as “Gaussian mixed modes” and “primary component analysis” are then used to decompose the measured electrical response of the devices into the known responses to each individual gas. As a consequence of these effects, the sensitivity of such devices to different gases does vary with temperature, although calibration can be used (as with all sensors) to produce accurate and reproducible readings (see Figure 3).

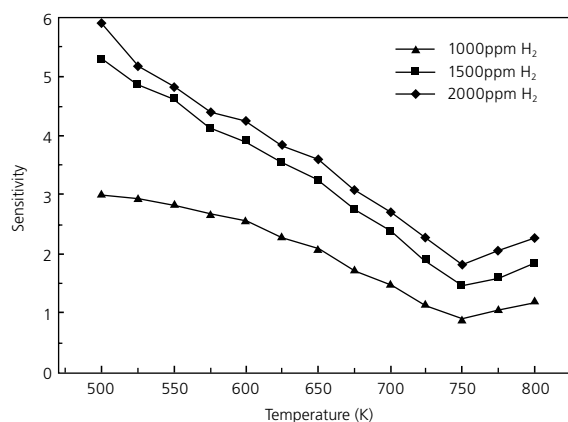


Figure 3. Variation in sensitivity with temperature for a typical SiC gas sensor (Figure reproduced with permission from ref. 14. © 2007 IEEE).



Conclusion

Silicon carbide has emerged as a crucial technological material in recent years; not just for mechanical use, but also as an electronic and optical material. Its excellent material properties and the emergence of underpinning material processing techniques promise a bright future for silicon carbide in many areas of science and engineering.

References:

- (1) Acheson, E.G. *J. Franklin Inst.* **1893**, 136, 279.
- (2) Acheson, E.G. To the Carborundum Co. U.S. Patent 492,767. Feb. 28, 1893.
- (3) Shaffer, P.T.B. *Acta Cryst.* **1969**, B25, 477.
- (4) Ramsdell, L.S. *Am. Mineral.* **1947**, 32, 64.
- (5) *Properties Of Silicon Carbide*, Harris, G.L., Ed.; INSPEC: London, 1995.
- (6) Silicon Carbide. *Kirk-Othmer Encyclopedia Of Chemical Technology*, 5th ed.; Wiley: New York, 2006; Vol 22.
- (7) Srinivasan, M. *Structural Ceramics, Treatise On Materials Science And Technology*; Wachtman, Jr., J.B., Ed.; Academic Press, Inc.: New York, 1989; Vol. 29.
- (8) Baliga, B.J. *Silicon Carbide Power Devices*, World Scientific Press: Singapore, 2006.
- (9) *Silicon Carbide: Recent Major Advances*; Choyke, W.J.; Matsunami, H.; Pensl, G., Eds.; Springer: Berlin, 2006.
- (10) Goldberg, Y.; Levinstein, M.; Romyantsev, S. *Properties Of Advanced Semiconductor Materials*; Levinstein, M.; Romyantsev, S.; Shur, M., Eds.; Wiley: New York, 2001.
- (11) *Silicon Carbide: Materials, Processing And Devices*; Feng, Z.C.; Zhao, J.H., Eds.; Taylor And Francis: New York, 2006.
- (12) Wright, N.G.; Horsfall, A. B. *Journal Of Physics D- Applied Physics*, **2007**, 40, 6345.
- (13) Weng, M.H.; Mahapatra, R.; Wright, N.G.; Horsfall, A.B. *Meas. Sci. Technol.*, **2008**, 19, 024002.
- (14) Weng, M.H.; Mahapatra, R.; Horsfall, A.B.; Wright, N.G. *IEEE Sensors Journal*, **2007**, 7, 1395.
- (15) Sigma-Aldrich Catalog (2009-2010).
- (16) Nakagomi, S.; Tobias, P.; Baranzahi, A.; Lundstrom, I.; Maretsson, P.; Spetz, A.L. *Sensors And Actuators B*, **1997**, 45, 183.
- (17) Baranzahl, A.; Spetz, A. L.; Glavmo, M.; Nytmot, J.; Lundstrom, I. *Proceedings, 8th International Conference on Solid-state Sensors and Actuators, and Eurosensors IX, Stockholm Sweden*, **1995**, 741.
- (18) Xiong, W.; Kale, G. *Sensors And Actuators B*, **2005**, 114, 101.

Silicon Carbide

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Name	Formula	Purity	Dimensions	Physical Form	Cat. No.
Silicon carbide	SiC	>95% by XRD	particle size 200 - 450 mesh	powder	378097-250G 378097-1KG
Silicon carbide	SiC	≥97.5%	particle size ~400 mesh	hexagonal phase powder	357391-250G 357391-1KG
Silicon carbide	SiC	>95% by XRD	particle size <100 nm	nanopowder	594911-100G 594911-250G

Metal Carbides

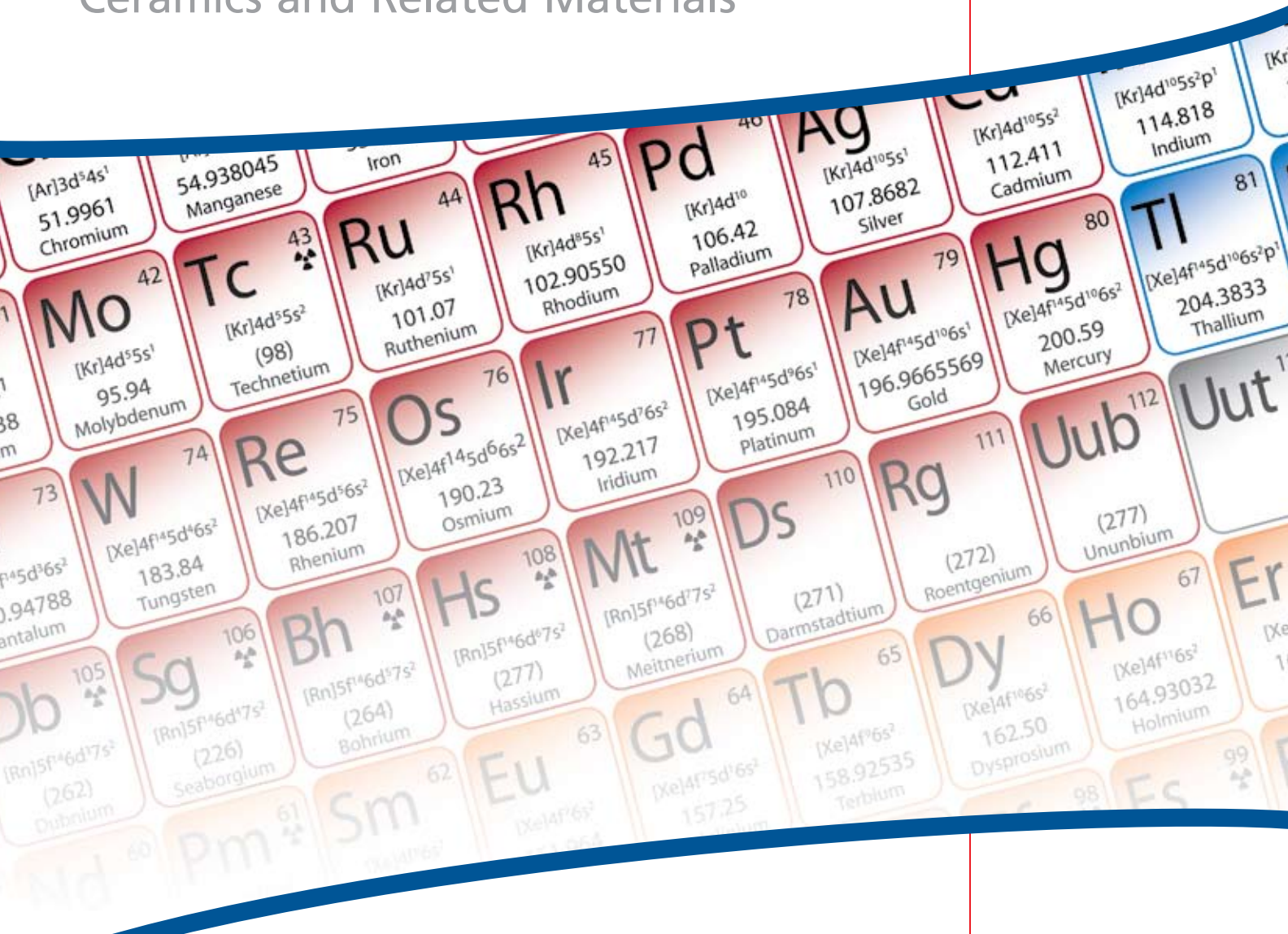
Name	Formula	Purity	Dimensions	Physical Form	Cat. No.
Aluminum carbide	Al ₄ C ₃	99%	~325 mesh	cubic phase powder	241873-25G 241873-100G
Tungsten(IV) carbide	WC	99%	10 μm	powder	241881-100G
Calcium carbide	CaC ₂	~80%	thickness <10 mm (typically)	pieces	270296-500G 270296-2KG
Calcium carbide	CaC ₂	≥75%, gas-volumetric	particle size 0.3 - 1 mm	pieces	21039-100G-F 21039-1KG-F
Tantalum(IV) carbide	TaC	99%	≤5 μm	powder	280801-10G
Titanium(IV) carbide	TiC	98%	~325 mesh	powder	307807-100G 307807-500G
Zirconium(IV) carbide	ZrC	99%	5 μm	cubic phase powder	336351-50G 336351-250G
Boron carbide	CB ₄	98%	10 μm	powder	378119-50G
Boron carbide	CB ₄	98%	~200 mesh	powder	378100-100G 378100-500G
Molybdenum carbide	Mo ₂ C	99.5%	~325 mesh	powder	399531-50G
Chromium carbide	Cr ₃ C ₂	99.5%	~325 mesh	powder	402680-50G 402680-250G
Hafnium(IV) carbide	HfC	-	particle size <1.25 μm	powder	594636-25G
Titanium(IV) carbide	TiC	≥95%	<4 μm	powder	594849-25G 594849-100G
Titanium(IV) carbide	TiC	95%	particle size <200 nm BET)	nanopowder	636967-25G 636967-100G 636967-250G

Silicides

Name	Formula	Purity	Dimensions	Physical Form	Cat. No.
Magnesium silicide	Mg ₂ Si	≥99% trace metals basis	~20 mesh	powder	343196-25G
Molybdenum disilicide	MoSi ₂	≥99% trace metals basis	-	powder	243647-250G
Tungsten silicide	WSi ₂	99.5%	~325 mesh	powder	399442-10G
Calcium silicide	CaSi ₂	-	-	powder	21240-250G-F 21240-1KG-F

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Mesoporous Oxides and Their Applications to Hydrogen Storage



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Introduction

Solid-state hydrogen storage is attractive from a technological point of view, but has encountered tremendous challenges in terms of practical storage capacity and kinetics.¹⁻³ Hydrogen sorption, whether it is chemisorption of dissociated atomic hydrogen or van der Waals weak physisorption of molecular hydrogen, depends strongly on material-specific surface interactions. High-surface area carbon materials and metal hydrides (including complex hydrides) represent two distinctive categories of candidate materials for solid-state hydrogen storage and have been the focus of intensive research.

More recently, metal-organic frameworks^{4,5} have emerged as an important class of physisorption hydrogen storage materials due to the possibility of designing them with functionalized porous structures as well as their low density and high specific surface area. On the other hand, reversible chemisorption materials, such as metal hydrides, exhibit high formula hydrogen storage capacities. However, their practical use is often limited by high thermodynamic stability (e.g., MgH_2) or poor reaction kinetics (e.g., Alanes). New approaches that simultaneously address reaction chemistry, compositional modifications, and reactant heat and mass transport are needed to overcome these barriers to realizing practical hydrogen storage. To address these issues, we base our approach on low density, metal oxide based, ceramic materials produced using sol-gel processing, then modifying those structures using a variety of methods to form modified active oxide networks.

Low Density Mesoporous Oxides

Mesoporous materials, such as aerogels, offer several advantages over other materials due to their large surface area (over 1000 m²/gm), open porosity (80 to 99.9% porous), small pore sizes (typically peaking at 10-20 nm), and the ability to coat the surface of the mesoporous structure with one or more compounds. These materials are made using sol-gel processing followed by drying using solvent extraction. If the solvent extraction is carried out using supercritical processing the resultant material is called an aerogel. Aerogels were discovered by Kistler in 1931.⁶ Kistler's pioneering work centered on demonstrating that a "gel" is made up of a solid framework containing the liquid from which it was formed. Because drying the gels in air causes them to shrink considerably and fracture into many pieces he surmised that surface tension forces were collapsing the submicroscopic pores. To avoid the surface tension forces he first substituted ethanol for the liquid in the gel, then raised the temperature and pressure above the critical point of ethanol (243.1°C and 63.1 bar) to eliminate the surface tension. At this point he slowly lowered the pressure, allowing the fluid to expand and leave the gel. He named the resulting material aerogel because it contained air rather than liquid. Alternatively, air dried gels are typically much denser and are termed xerogels.

Aerogels have been proposed for a wide variety of applications because of their unique properties. They are the lightest solid materials, with up to 99.7% porosity, transparent and excellent solid thermal insulators. In addition, aerogels have the lowest sound conductivity of any material (less than 100 m/sec, the sound velocity in air is 343 m/sec). They have been used to prepare Cherenkov counters, superinsulating windows, solar collector covers, refrigerators, spacecraft, water heaters and pipe insulation. Unique shock wave characteristics of ceramic aerogels led to their use as space dust collectors in earth orbit and the Stardust mission to the comet Wilde II which returned the first meteoric dust to earth. Aerogels have also been tested as high performance electrical insulation because of their high breakdown voltage, as catalysts due to their high surface area, for gas filters because of their fine pore sizes, for vapor phase pumps driven by temperature differences and aided by their hydrophilic nature, toxic cleanup materials, elements of acoustic devices and even safe insecticides.

An open pore aerogel structure may be made from many inorganic oxides, carbon, or polymers. In fact, aerogel mesoporous materials may be thought of as a "three dimensional canvas" that can be "painted" with a variety of materials on a nonporous scale. Great flexibility is afforded by this material's processing technique because of the variety of backbone structures that can be produced and the ability to incorporate a large variety of additional constituents.^{7,8} This can be accomplished by modifying or adding functional groups to the sol gel precursor, or by chemical vapor infiltration (CVI) after the solvent has been extracted from the pores. CVI is chemically similar to chemical vapor deposition, CVD, but occurs inside a porous material. Using these techniques, it is possible to use substantial amounts of materials to coat the backbone with several times its volume. Thus, this approach to building mesoporous materials offers a flexible and cost effective route to a variety of materials tailored at the nanoscale for hydrogen storage as well as other applications.



We have been investigating the preparation and properties of ultra-low density nanomaterials based on aerogel technology since 1980. We also developed a technique to substitute nonflammable carbon dioxide for alcohol in the gel and perform the supercritical drying at lower temperatures (31.1°C and 73.0 bars).⁹ A wide variety of aerogel compositions have been prepared including metal oxides (SiO_2 , TiO_2 , Fe_3O_4 , Al_2O_3 , MgO , Cr_2O_3 , Zr_2O_3), mixed oxides, and other compounds.¹⁰ Many of these have had additional coatings or deposits using pre- and post-supercritical drying treatments.^{11,12} A wide variety of elements and compounds have been deposited using sol-gel chemistry, solvent additions and Chemical Vapor Infiltration. The most widely investigated combination is silica aerogel coated with carbon using CVI with acetylene. **Figure 1** illustrates a pure silica aerogel and a carbon doped silica aerogel. As a measure of the effectiveness of this process we have achieved from 1% to 400% loading of carbon into the silica (four times more carbon mass than silica).



Figure 1. Photographs showing un-doped (left) and carbon-doped (right) ultra-low density SiO_2 network material.

Mesoporous Oxides for Hydrogen Storage

One of the key advantages of using ultralow density ceramic materials arises because of the size of the pores and the composition and functionality of the oxide backbone materials. Aerogels can be readily modified by changing the synthesis parameters. One modification approach is to vary the mixtures of precursors during preparation (the sol-gel stage). For instance, one can dope $\text{Si}(\text{OAlk})_4$ (Aldrich Prod. Nos. [679321](#), [679259](#), [679240](#), [T5702](#), [333859](#)) or $\text{Ti}(\text{OAlk})_4$ (Aldrich Prod. Nos. [252670](#), [244112](#), [462551](#), [244759](#), [333484](#), [377996](#), [463582](#), [253081](#)) with transition metal salts or boron compounds. During hydrolysis, transition metals can be incorporated into the oxide network. If functionalized dopants are employed, such as $\text{A-CH}_2\text{-Si}(\text{OAlk})_3$ (Aldrich Prod. Nos. [679267](#), [679356](#), [679291](#), [679275](#)) or $\text{(A-CH}_2\text{)}_2\text{Si}(\text{OAlk})_2$ (Aldrich Prod. Nos. [371890](#), [435171](#), [539260](#), [446173](#)), one can introduce additional chemisorption centers in the oxide network materials by coordinating A to transition metals (added after the network structure is formed). Additionally, the network material properties can be tuned by varying the compositions of the coatings, which would lead to applications far beyond hydrogen storage.

Once the mesoporous oxide networks are prepared, several approaches can be used to modify them. An example of the modification strategy, used to prepare X-SiO_2 porous networks, is depicted in **Figure 2**, where X may be a high-capacity hydride compound, intercalated within the array of SiO_2 nanoparticles of the aerogel, and filling a significant fraction of the pore space.

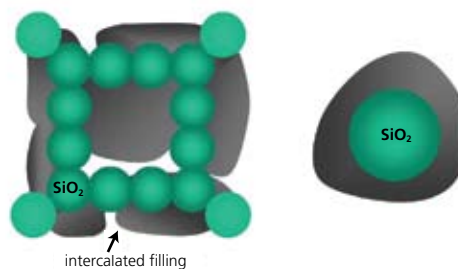


Figure 2. Schematic illustration of a strategy of modified active oxide networks. The right illustration represents individual hydride-X coated oxide nanostructure, forming an X-SiO_2 .

A schematic illustration (in two-dimensional projection plane) of the ultralow-density oxide network material is given in **Figure 3a**. It consists of a network of silica nanoparticles, approximately 3 nm in diameter, with a system of nanopores far smaller than the wavelength of visible light, typically 10 nm. **Figure 3b** is a transmission electron microscopy (TEM) image of a synthesized sample, illustrating that the highly porous medium consists of a network of randomly positioned silica nanoparticles. The specific surface area of the un-coated silica network is typically $1000 \text{ m}^2/\text{g}$ as measured by BET, and the bulk density is about 0.08 g/cm^3 .

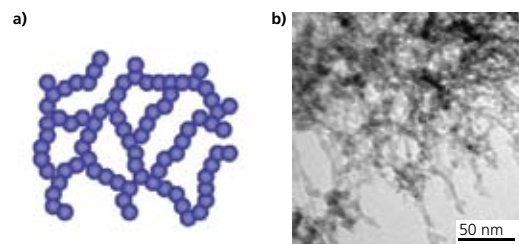


Figure 3. (a) Schematic illustration of a material consisting of a network of silica nanoparticles (b) TEM image of an ultralow-density silica oxide network sample.

We investigated the baseline properties of SiO_2 ceramic nanoparticle networks for hydrogen storage to better understand and evaluate the effects of further modification of the materials. We found the SiO_2 nanoparticle networks have favorable hydrogen storage properties through physisorption due to their very large surface area. Nevertheless, the storage capacity of the network does not yet meet the US DOE's gravimetric and volumetric targets. The adsorbed capacity of an ultralow density silica network at liquid nitrogen temperature is shown in **Figure 4**. Measurements were conducted using a volumetric hydrogen storage testing system (PCTPro, Hy-Energy; see reference 13 for details). It can be seen that the hydrogen adsorption capacity increases monotonically to 40 bar and continues to rise with pressure.

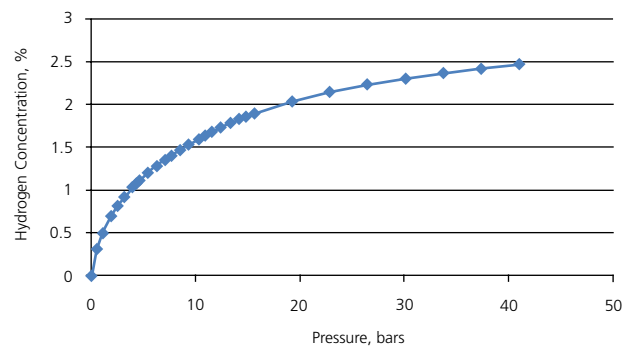
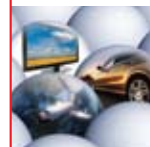


Figure 4. Hydrogen storage capacity of ultralow density silicon network vs. pressure in bars.



To increase the density of stored hydrogen we introduce chemisorption into this system, while maintaining the benefit of the high-surface area for additional storage through functionalized physisorption. At the same time, the high-surface area nanoparticle network should provide the additional benefit of markedly improved chemisorption kinetics by increasing reaction surface area as well, as reducing diffusion distance (of hydrogen as well as constituent reactants).

As a proof of concept experiment, we fabricated a composite material using MgNi (<5 wt.%) implemented in an ultralow-density SiO₂ aerogel nanoparticle network. Using magnesium, a structure was formed with 7.6 wt.% hydride, MgH₂ (**Aldrich Prod. No. 683043**), but is generally hindered by poor kinetics caused by limited diffusion of hydrogen through the hydride. Ni is an effective catalyst for hydrogen dissociation and when combined with Mg may form the intermetallic compound Mg₂Ni which also forms a hydrogen-rich complex hydride Mg₂NiH₄.

The composite network was prepared by a two-step process, starting with the pH-dependent hydrolysis and condensation of an alkoxysilane in alcohol, followed by CO₂ substitution and supercritical drying. Under a high vacuum environment, the resulting SiO₂ nanoparticle network was subjected to vapor infiltration of Mg and Ni through the use of a physical or a chemical vapor deposition process (we used a pulsed laser to vaporize a solid state MgNi alloy target). Preliminary measurements indicate chemisorption of hydrogen in the modified silica network, in addition to physisorption due to the very large surface area offered by the oxide network.

A technological advantage presented by the modified active oxide networks is their scalability. We have demonstrated large scale manufacturing feasibility of nanostructured oxide networks based on supercritical drying/sol-gel process and chemical vapor infiltration/deposition for incorporating desired compound through

the mesopores of the oxide network. These ultralow density materials can be fabricated with varying density, structure and shape. Monolithic squares up to 20 inches on a side have been synthesized at Berkeley; they would be suitable for on-board transportation applications. With this scale-up manufacturing possibility, ultralow density active ceramic networks represent a clear alternative to existing porous media for solid-state hydrogen storage.

Summary

The above proof-of-concept experiments and analyses demonstrate the potential of the ultralow-density modified active oxide networks. While the hydrogen storage capacity of the mesoporous ceramic networks are not yet sufficient, it is our goal to modify them in order to achieve desired hydrogen storage capacity and kinetics. The optimized performance of the new materials can be realized by process modifications that include tuning the structure and specific surface area of the active oxide networks and implementing different combinations of catalytic and chemisorbing phases.

References:

- (1) Satyapal, S.; Petrovic, J.; Read, C.; Thomas, G.; Ordaz, G. *Catalysis Today* **2007**, *120*, 246.
- (2) Schlapbach, L.; Zuttel, A. *Nature* **2001**, *414*, 353.
- (3) Bogdanovic, B.; Sandrock, G. **2002 MRS Bulletin**, September 712.
- (4) Rosi, N.L.; Eckert, J.; Eddaoudi, M.; Vodak, D.T.; Kim, J.; O'Keeffe, M.; Yaghi, O.M. *Science* **2003** *300*, 1127.
- (5) Rowsell, J.L.C.; Yaghi, O.M. *Angew. Chem. Int. Ed.* **2005**, *44*, 4670.
- (6) Kistler, S.S. *Nature*, **1931** 227, 741.
- (7) Mao, S. S.; Carrington, K. R.; Chen, X.; Hunt, A.; Gross, K., Hydrogen storage in ultra-low density silica aerogel, private communication.
- (8) Ayers, M.R.; Song, X.Y.; Hunt, A.J. *J. Mat. Sci.* **1996** *31*, 6251.
- (9) Tewari, P.H.; Hunt, A.J.; Lofftus, K.D. *Mat. Lett.* **1985** *3*, 363.
- (10) Hunt, A. *Encyclopedia Britannica Science Year Book*, **1996** 146.
- (11) Hunt, A.J.; Ayers, M.R.; Cao, W. *J. Non-Cryst. Solids* **1995** *185*, 227.
- (12) Balema, V. P. *Material Matters* **2006** *1*, 3.
- (13) Gross, K. *Material Matters* **2006**, *2*, 2, 26.

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Product Name	Cat. No.
Trimethylaluminum	663301
Tetrakis(dimethylamido)hafnium(IV)	666610
Diethylzinc	668729
Bis(<i>tert</i> -butylimino)bis(dimethylamino)tungsten(VI)	668885
Tris(diethylamido)(<i>tert</i> -butylimido)tantalum(V)	668990
Tetrakis(dimethylamido)titanium(IV)	669008
Tetrakis(dimethylamido)zirconium(IV)	669016

Product Name	Cat. No.
Bis(ethylcyclopentadienyl)ruthenium(II)	679798
Titanium(IV) isopropoxide	687502
Silicon tetrachloride	688509
Titanium tetrachloride	697079
Tris(<i>tert</i> -butoxy)silanol	697281
Tris(<i>tert</i> -pentoxy)silanol	697303
Tris[<i>N,N</i> -bis(trimethylsilyl)amide]yttrium	702021

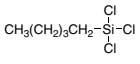

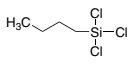
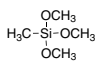
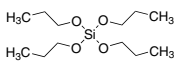
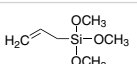
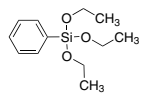
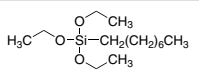
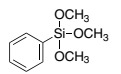
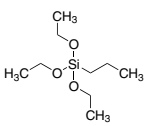
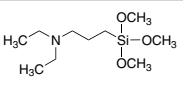
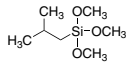
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Chloro- and Alkoxysilanes

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Name	Structure	Purity	Physical Form	Cat. No.
Pentyltrichlorosilane		≥98% deposition grade	liquid	679194-50G
Methyltrichlorosilane		≥98%, GC ≥99.99% (as metals) deposition grade	liquid	679208-50G
Ethyltrichlorosilane		≥98%, GC ≥99.99% (as metals) deposition grade	liquid	679216-50G
Butyltrichlorosilane		≥98% deposition grade	liquid	679224-50G
Trimethoxymethylsilane		≥98% deposition grade	liquid	679232-50G
Tetrapropyl orthosilicate		≥98% deposition grade	liquid	679240-50G
Tetramethyl orthosilicate		≥99.9% trace metals basis ≥98% deposition grade	liquid	679259-50G
Allyltrimethoxysilane		≥98% deposition grade	liquid	679267-50G
Triethoxyvinylsilane		≥98% deposition grade	liquid	679275-50G
Triethoxyphenylsilane		≥98% deposition grade	liquid	679291-50G
Triethoxy(octyl)silane		99.99% trace metals basis 98% deposition grade	liquid	679305-50G
Trimethoxyphenylsilane		≥98% deposition grade	liquid	679313-50G
n-Propyltriethoxysilane		≥98% deposition grade	liquid	679321-50G
[3-(Diethylamino)propyl]trimethoxysilane		≥98% deposition grade	liquid	679356-50G
Isobutyl(trimethoxy)silane		≥98% deposition grade	solution	679364-50G

Metal Alkoxides

For a complete list of sol-gel precursors, please visit sigma-aldrich.com/solgel

Name	Structure	Purity/Concentration	Physical Form	Cat. No.
Magnesium acetate		99.999% trace metals basis	solid	229768-10G 229768-100G
Magnesium acetylacetonate		98%	solid	129577-25G
Magnesium methoxide	Mg(OCH ₃) ₂	6-10 wt. % in methanol	-	335657-500ML 335657-2L
Magnesium ethoxide		98%	granular	291846-100G 291846-500G
Aluminum acetylacetonate		99.999%	solid	674753-5G 674753-25G
Aluminum phenoxide		99.9% trace metals basis	solid	495131-5G 495131-25G
Aluminum-tri-sec-butoxide		97%	liquid	201073-5G 201073-100G 201073-500G
Titanium(IV) isopropoxide		97%	liquid	205273-5ML 205273-100ML 205273-500ML 205273-2L
Aluminum acetylacetonate		99%	solid	208248-5G 208248-100G 208248-500G
Aluminum isopropoxide		≥99.99% trace metals basis	solid	229407-10G 229407-50G 229407-250G
Aluminum isopropoxide		≥98%	solid	220418-100G 220418-1KG
Aluminum tert-butoxide		-	powder	235849-10G 235849-50G
Aluminum ethoxide		97%	solid	235857-5G 235857-25G 235857-100G
Aluminum acetate, basic		-	powder	294853-250G 294853-1KG
Diethylaluminum ethoxide		97%	liquid	256749-100G
Aluminum tributoxide		95%	solid	403350-5G 403350-25G
Aluminum-tri-sec-butoxide		99.99% trace metals basis	liquid	511609-5G
Aluminum tri-sec-butoxide		1.0 M in methylene chloride	solution	558907-500ML
Titanium(IV) methoxide	Ti(OCH ₃) ₄	≥99.99% trace metals basis	solid	463582-25G
Titanium(IV) methoxide	Ti(OCH ₃) ₄	95%	solid	404950-10G 404950-50G
Titanium(IV) ethoxide		-	liquid	244759-50G 244759-250G
Titanium(IV) butoxide		97%	liquid	244112-5G 244112-100G 244112-500G 244112-2KG



Name	Structure	Purity/Concentration	Physical Form	Cat. No.
Titanium(IV) <i>tert</i> -butoxide		-	liquid	462551-25ML 462551-50ML
Titanium(IV) propoxide		98%	liquid	253081-100G 253081-500G
Titanium(IV) isopropoxide		99.999% trace metals basis	liquid	377996-5ML 377996-25ML 377996-100ML
Titanium diisopropoxide bis(acetylacetonate)		75 wt. % in isopropanol	solution	325252-100ML 325252-500ML
Titanium(IV) oxide acetylacetonate		95%	powder	330833-10G 330833-50G
Titanium(IV) 2-ethylhexyloxide		95%	liquid	333484-250ML
Chlorotrisisopropoxytitanium(IV)		95%	liquid	250627-100G 250627-800G
Chlorotrisisopropoxytitanium(IV)		1.0 M in hexanes	solution	252670-100ML 252670-800ML
Zirconium(IV) ethoxide		97%	solid	339121-5G 339121-25G
Zirconium(IV) butoxide	$Zr(OCH_2CH_2CH_2CH_3)_4$	80 wt. % in 1-butanol	solution	333948-100ML 333948-500ML 333948-2L
Zirconium(IV) <i>tert</i> -butoxide		99.999% trace metals basis	liquid	560030-5G 560030-25G
Zirconium(IV) propoxide		70 wt. % in 1-propanol	solution	333972-100ML 333972-500ML
Zirconium(IV) isopropoxide isopropanol complex		99.9% trace metals basis	powder	339237-10G 339237-50G
Zirconium acetate		in dilute acetic acid	liquid	413801-500ML 413801-2L
Zirconium(IV) acetate hydroxide		-	powder	464600-100G 464600-500G
Zirconium(IV) acetylacetonate		98%	powder	338001-25G 338001-100G
Zirconium(IV) trifluoroacetylacetonate		97%	solid	383325-1G
Zirconium(IV) bis(diethyl citrato) dipropoxide		-	liquid	515817-1L

Titanates

Name	Formula	Purity	Dimensions	Physical Form	Cat. No.
Lithium titanate	Li_2TiO_3	-	-325 mesh	powder	400939-100G 400939-500G
Lithium titanate, spinel	$\text{Li}_4\text{Ti}_5\text{O}_{12}$	>99%	particle size <100 nm TEM) particle size <100 nm BET)	nanopowder	702277-25G
Aluminum titanate	$\text{Al}_2\text{O}_3\cdot\text{TiO}_2$	98.5% trace metals basis	particle size <25 nm BET)	nanopowder	634131-20G 634131-100G
Aluminum titanate	$\text{Al}_2\text{O}_3\cdot\text{TiO}_2$	-	-	powder	520209-250G
Titanium silicon oxide	$(\text{SiO}_2)(\text{TiO}_2)$	99.8% trace metals basis	particle size <50 nm BET)	nanopowder	641731-10G 641731-50G
Calcium titanate	CaTiO_3	99.9% trace metals basis	particle size <100 nm BET) particle size <50 nm XRD)	nanopowder	633801-25G 633801-100G
Calcium titanate	CaTiO_3	99%	-325 mesh	powder	372609-2KG
Iron(II) titanate	FeTiO_3	99.9%	-100 mesh	powder	400874-25G 400874-100G
Zinc titanate	$\text{ZnTiO}_4 \cdot \text{ZnTiO}_2$	99.5% trace metals basis	particle size <100 nm BET) particle size <50 nm XRD)	nanopowder	634409-25G 634409-100G
Strontium titanate	SrTiO_3	$\geq 99.5\%$ trace metals basis	particle size <100 nm	nanopowder	517011-50G
Strontium titanate	SrTiO_3	99%	5 μm	powder	396141-100G 396141-500G
Strontium titanate	SrTiO_3	$\geq 99.99\%$ trace metals basis	10 x 10 x 0.5 mm	<110> single crystal substrate single side polished crystalline (cubic (a = 3.905 Å))	634670-1EA
Strontium titanate	SrTiO_3	99.99% trace metals basis	10 x 10 x 0.5 mm	<111> single crystal substrate single side polished	638161-1EA
Strontium titanate	SrTiO_3	-	10 x 10 x 0.5 mm	<100> single crystal substrate crystalline (cubic (a=3.905 Å))	634689-1EA
Barium titanate(IV)	BaTiO_3	99.995% trace metals basis	-	powder	256552-10G 256552-50G
Barium titanate(IV)	BaTiO_3	$\geq 99\%$ trace metals basis	particle size <100 nm BET)	nanopowder (cubic crystalline phase)	467634-25G 467634-100G
Barium titanate(IV)	BaTiO_3	99.9% trace metals basis	3 - 12 mm	pieces sintered	342939-50G
Barium titanate(IV)	BaTiO_3	99.9% trace metals basis	<2 μm	powder	338842-100G 338842-500G
Barium titanate(IV)	BaTiO_3	99%	<3 μm	powder	208108-500G 208108-2KG
Barium titanate(IV)	BaTiO_3	$\geq 98.0\%$	particle size <3 μm	powder	11848-1KG
Neodymium(III) titanate	$2\text{Nd}_2\text{O}_3 \cdot 5\text{TiO}_2$	-	-325 mesh	powder	403695-500G
Lead(II) titanate	PbTiO_3	$\geq 99\%$	<5 μm	powder	215805-250G
Bismuth(III) titanate	$\text{Bi}_2\text{O}_3 \cdot 2\text{TiO}_2$	-	-325 mesh	powder	403687-100G



Tungstates

Name	Formula	Purity	Dimensions	Physical Form	Cat. No.
Lithium tungstate	Li_2WO_4	98%	-	powder	400912-25G 400912-100G
Ammonium tungstate	$(\text{NH}_4)_{10}\text{H}_2(\text{W}_2\text{O}_7)_6$	99.99% trace metals basis	-	powder	322385-10G 322385-50G
Sodium tungstate	$\text{Na}_2\text{WO}_4 \cdot 2\text{H}_2\text{O}$	99.995% trace metals basis	-	chunks	379751-5G 379751-25G
Sodium phosphotungstate	$\text{Na}_3\text{PO}_4 \cdot 12\text{WO}_3 \cdot x\text{H}_2\text{O}$	≥99.9% trace metals basis	-	powder	496626-25G 496626-100G
Sodium phosphotungstate	$\sim 2\text{Na}_2\text{O} \cdot \text{P}_2\text{O}_5 \cdot 12\text{WO}_3 \cdot 18\text{H}_2\text{O}$	-	-	powder	P6395-25G P6395-100G P6395-500G
Magnesium tungstate	MgWO_4	99.9% trace metals basis	-325 mesh	powder	415073-10G 415073-50G
Potassium tungstate	K_2WO_4	≥99.99% trace metals basis	-	powder	483079-5G 483079-25G
Potassium tungstate	K_2WO_4	94%	-100 mesh	powder	372617-100G
Calcium tungstate	CaWO_4	-	-	powder	248665-100G 248665-500G
Strontium tungsten oxide	SrWO_4	99.9% trace metals basis	-200 mesh	powder	709220-10G
Silver tungstate	Ag_2WO_4	99.99% trace metals basis	-	powder	587362-10G
Cadmium tungstate	CdWO_4	-	-325 mesh	powder	401129-5G 401129-25G
Barium tungstate	BaWO_4	99.9% trace metals basis	-100 mesh	powder	343137-50G
Barium yttrium tungsten oxide	$\text{Ba}_3\text{Y}_2\text{WO}_9$	99.9%	<5 μm	powder	415170-25G
Bismuth tungsten oxide	$\text{Bi}_2(\text{WO}_4)_3$	-	-200 mesh	powder	709239-10G

Zirconates

Name	Formula	Purity	Dimensions	Physical Form	Cat. No.
Lithium zirconate	Li_2ZrO_3	-	-80 mesh	powder	400920-25G 400920-100G
Sodium zirconate	Na_2ZrO_3	-	-200 mesh	powder	400661-5G 400661-25G
Calcium zirconate	CaZrO_3	99.7% trace metals basis	particle size <25 nm XRD) particle size <50 nm BET)	nanopowder	631965-25G 631965-100G
Strontium zirconate	SrZrO_3	-	10 μm	powder	396168-250G
Barium zirconate	BaZrO_3	98.5% trace metals basis	particle size <50 nm	nanopowder	631884-25G 631884-100G
Barium zirconate	BaZrO_3	-	<10 μm	powder	383309-250G
Lead(II) zirconate	PbZrO_3	99% trace metals basis	-325 mesh	powder	398888-50G 398888-250G

Niobates

Name	Formula	Purity	Dimensions	Physical Form	Cat. No.
Lithium niobate	LiNbO_3	99.9% trace metals basis	200 mesh	powder	254290-10G 254290-100G
Ammonium fluoroniobate	$^5[\text{NH}_4^+] [\text{Nb}(\text{O})\text{F}_4 \cdot 2\text{NbF}_7 \cdot 2^-]$	99.99%	-	powder	525707-10G
Sodium niobate	NaNbO_3	99.9%	-100 mesh	powder	400653-5G 400653-25G
Potassium niobate	KNbO_3	-	-	powder	541206-25G
Potassium heptafluoroniobate(V)	K_2NbF_7	98%	-	powder	336645-25G
Zinc niobate	$\text{Zn}(\text{NbO}_3)_2$	97%	-	powder	548588-50G
Lead magnesium niobate	$(\text{PbO})_3(\text{MgO})(\text{Nb}_2\text{O}_5)$	≥99%	-	powder	672874-25G

Aldrich Materials for Solid Oxide Fuel Cell Applications

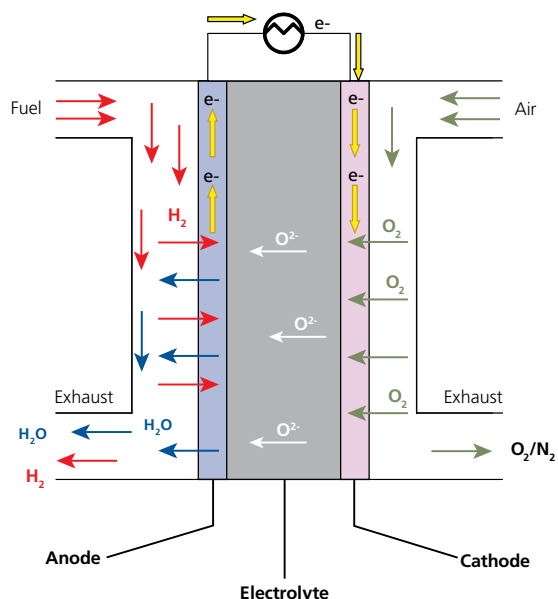
A fuel cell is a battery-like system that uses hydrogen and oxygen to generate electricity by an electrochemical reaction. Similar to other batteries, the fuel cell consists of two electrodes (porous anode and cathode) and an electrolyte (**Figure 1**).

In Solid Oxide Fuel Cells (SOFCs), the cathode and the anode are made from porous ceramic materials and the electrolyte consists of a dense oxygen ion conducting ceramic. This allows SOFCs to operate at high temperatures around 1,000°C (1,830°F) and to reform hydrocarbons internally, thus enabling the use of natural gas or reformed diesel as fuel.¹

The high-temperature operation places rigorous durability requirements on cell components. Therefore development of low-cost materials with high durability at high temperatures is the key technical challenge for SOFC technology.²

Aldrich Materials Science offers a variety of materials that can be used for the preparation of cathodes, anodes and electrolytes for SOFC applications. Our product portfolio includes a variety of Yttria Stabilized Zirconia (YSZ), Lanthanum Strontium Manganite (LSM), Gadolinium doped Ceria (GDC) and other ceramic materials specifically designed for SOFC applications.

For complete list of our fuel cell materials and related products, please visit sigma-aldrich.com/energy



References:

1. *High Temperature and Solid Oxide Fuel Cells. Fundamentals, Design and Applications;* Singhal, S.C., Kendal, K. Eds.; Elsevier: Amsterdam, The Netherlands, 2003.
2. *U.S. Department of Energy. Energy Efficiency and Renewable Energy. The Hydrogen, Fuel Cells & Infrastructure Technologies Program.* www1.eere.energy.gov/hydrogenandfuelcells/fuelcells/ (last accessed May 5, 2009)

Cathode Materials

Material Name	Composition	Cat. No.
Lanthanum strontium manganite	(La _{0.80} Sr _{0.20}) _{0.95} MnO ₃ , 50% Ce _{0.9} Gd _{0.1} O _{1.95} , 50%	704237-10G
Lanthanum strontium manganite, ≥99%	(La _{0.80} Sr _{0.20})MnO ₃ , 50% (Y ₂ O ₃) _{0.08} (ZrO ₂) _{0.92} , 50%	704245-10G
Lanthanum strontium cobalt ferrite	(Ce _{0.9} Gd _{0.1})O _{1.95} , 50% (La _{0.60} Sr _{0.40})(Co _{0.20} Fe _{0.80})O ₃ , 50%	704253-10G
Lanthanum strontium manganite, ≥99%	(Ce _{0.9} Gd _{0.1})O _{1.95} , 50% (La _{0.80} Sr _{0.20})MnO ₃ , 50%	704296-10G

Anode Materials

Material Name	Composition	Cat. No.
Nickel oxide - Yttria-stabilized zirconia	Nickel oxide, 66 wt. % Yttria-stabilized zirconia, 34 wt. %	704202-10G
Nickel oxide - Cerium samarium oxide, ≥99% trace metals basis	Cerium Samarium Oxide, 40 wt. % Nickel Oxide, 60 wt. %	704210-10G

Electrolytes

Material Name	Composition	Cat. No.
Zirconium(IV) oxide-yttria stabilized	O ₂ Zr/yttria 3% as stabilizer	572322-25G
Zirconium(IV) oxide-yttria stabilized	O ₂ Zr/yttria ~8% as stabilizer	464228-100G 464228-500G
Zirconium(IV) oxide-yttria stabilized	O ₂ Zr/yttria ~5.3% as stabilizer	464201-100G 464201-500G
Cerium(IV) oxide-gadolinium doped	CeO ₂ /gadolinium 10 mol % as dopant	572330-25G
Zirconium(IV) oxide-yttria stabilized	O ₂ Zr/yttria 8% as stabilizer	572349-25G
Cerium(IV) oxide-gadolinium doped	CeO ₂ /gadolinium 20 mol % as dopant	572357-25G
Cerium(IV) oxide-samarium doped	CeO ₂ /samaria 15 mol % as dopant	572365-25G
Cerium(IV) oxide-yttria doped	CeO ₂ /yttria 15 mol % as dopant	572381-25G

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